

CTAデュアルミラー光学系用 焦点面検出器の試作器開発

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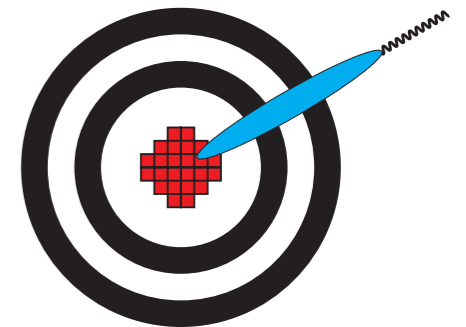
University of Wisconsin, Madison

Richard White, Jim Hinton

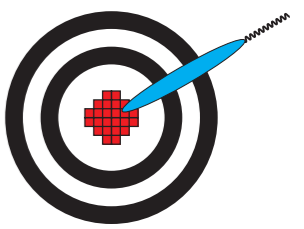
Department of Physics and Astronomy, University of Leicester



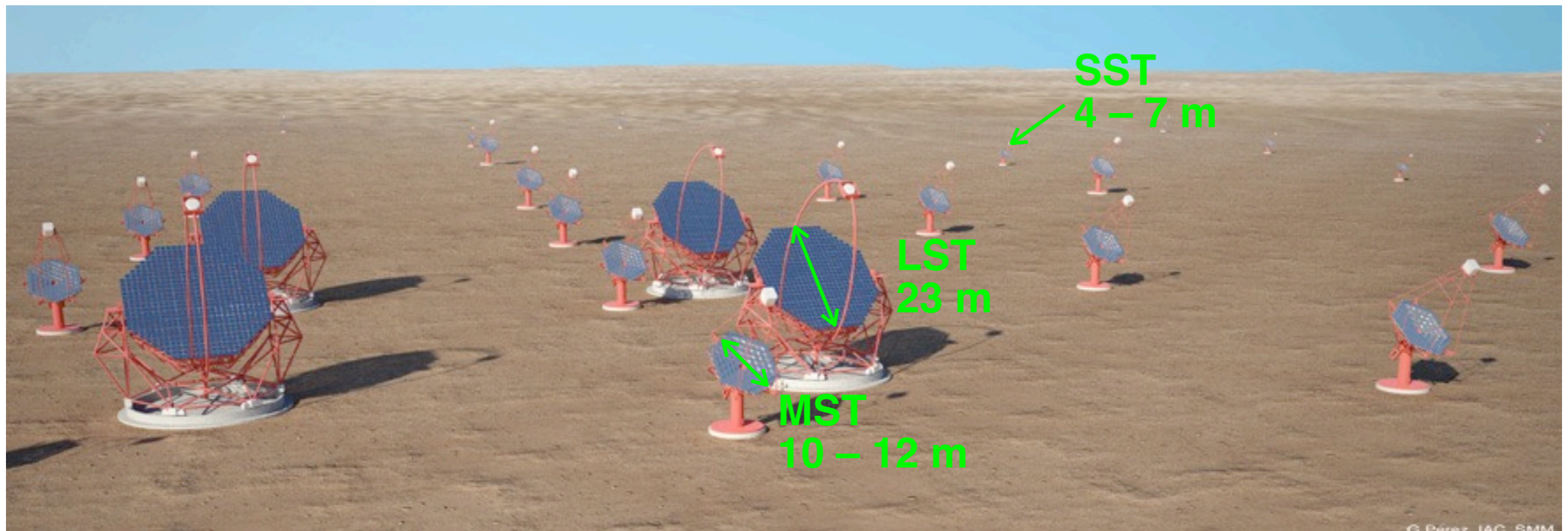
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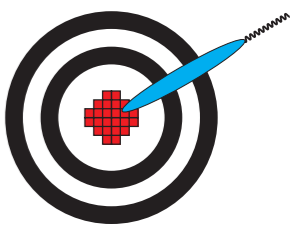


September 20, 2013
JPS meeting
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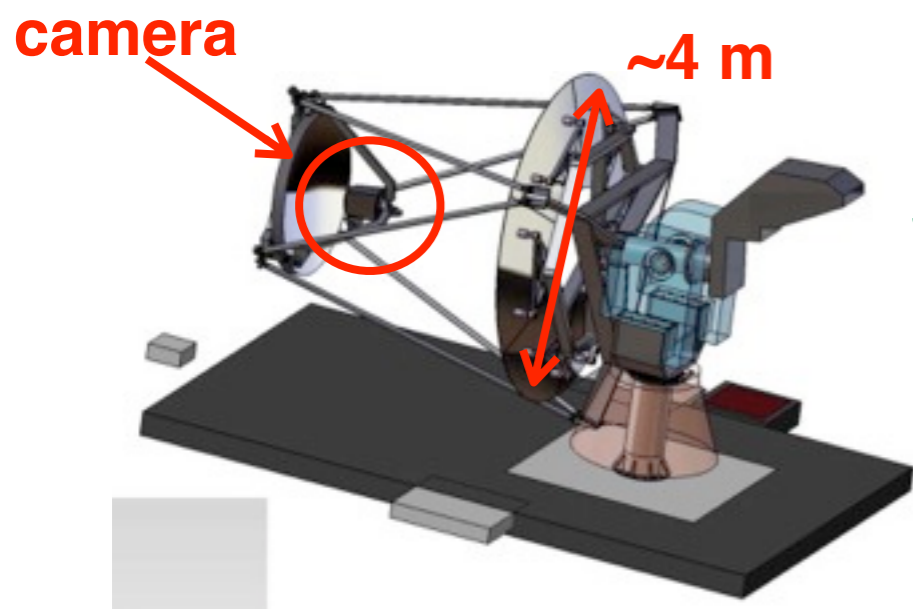


- ❖ Observations of gamma rays in 20 GeV – 100 TeV band
 - ❖ Cherenkov light from electromagnetic shower produced by interaction of gamma rays with atmosphere
- ❖ Large collection area by placing many telescopes
 - ❖ x10 better sensitivity
- ❖ Wide energy band coverage by three different size of telescopes
 - ❖ Large-size telescope (LST): $\Phi = 23$ m, 20 GeV – 1 TeV, 4 telescopes
 - ❖ Medium-size telescope (MST): $\Phi = 10 - 12$ m, 0.1 – 10 TeV, ~20 telescopes
 - ❖ Small-size telescope (SST): $\Phi = 4 - 7$ m, 1 – 100 TeV, 30 – 70 telescopes



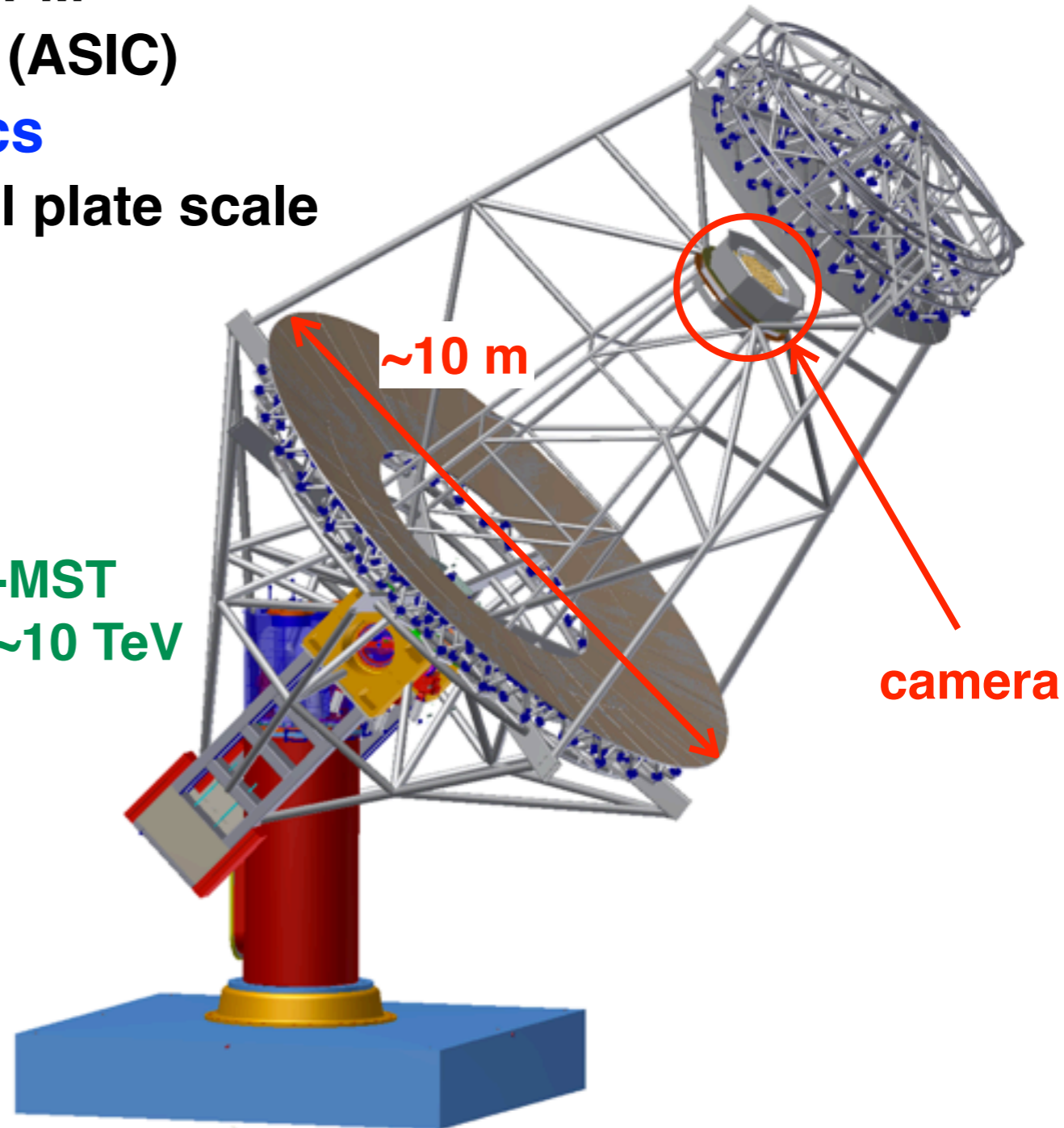


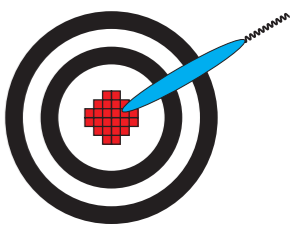
- ❖ **Dual mirror design with small pixel photon sensor**
 - ❖ **Small pixel (~6 mm) photon sensor to reduce camera cost**
 - ◆ Multi-anode photomultiplier or SiPM
 - ◆ High density readout electronics (ASIC)
 - ❖ **Schwarzschild-Couder (SC) optics**
 - ◆ Short focal length to realize small plate scale
 - Technically challenging
 - ◆ Large field of view
 - Longer telescope spacing (larger collection area)



SC-SST
1~100 TeV

SC-MST
0.1~10 TeV

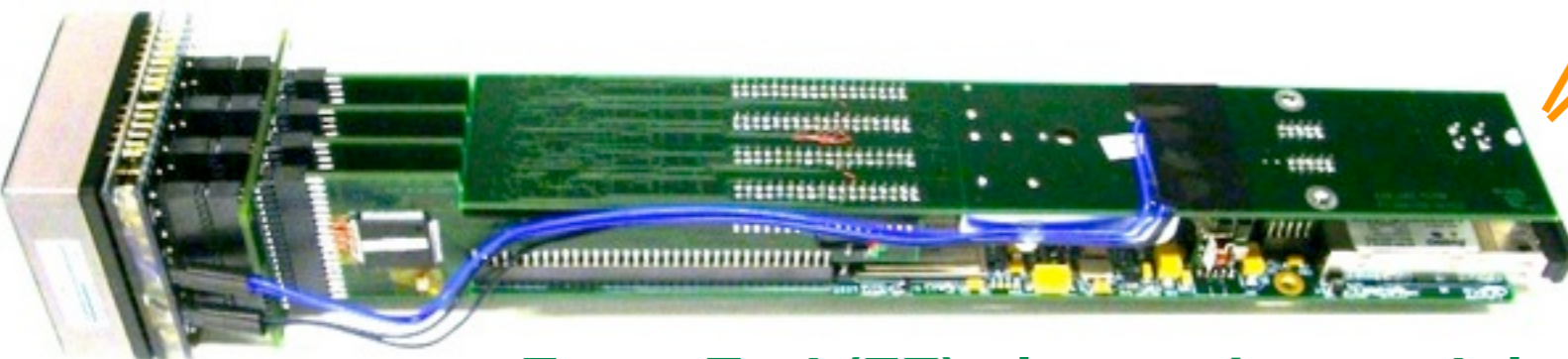
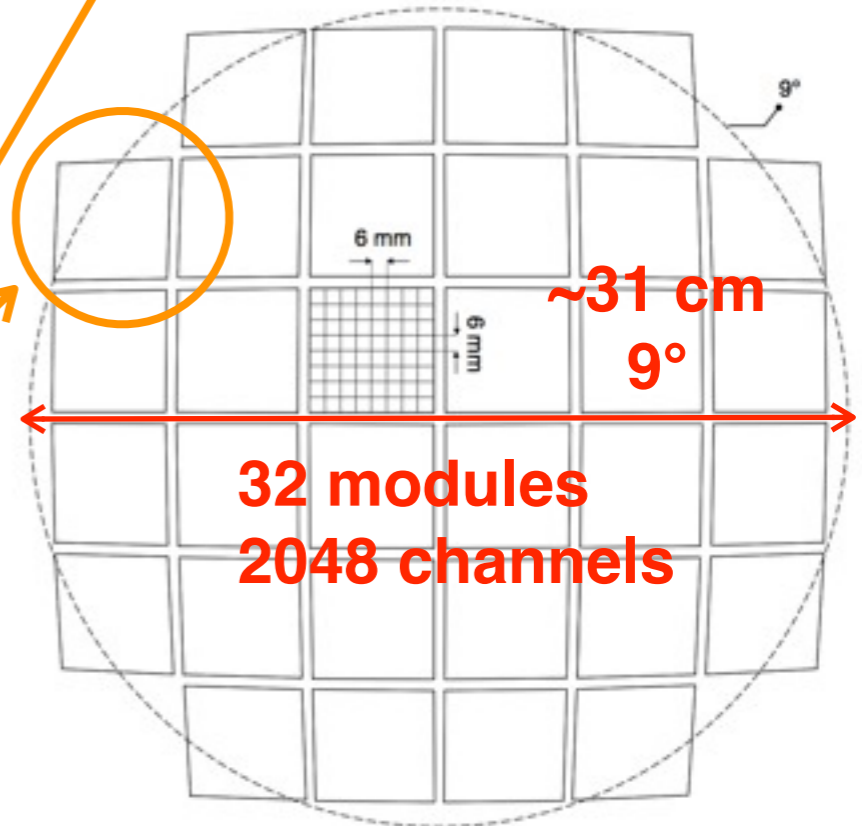
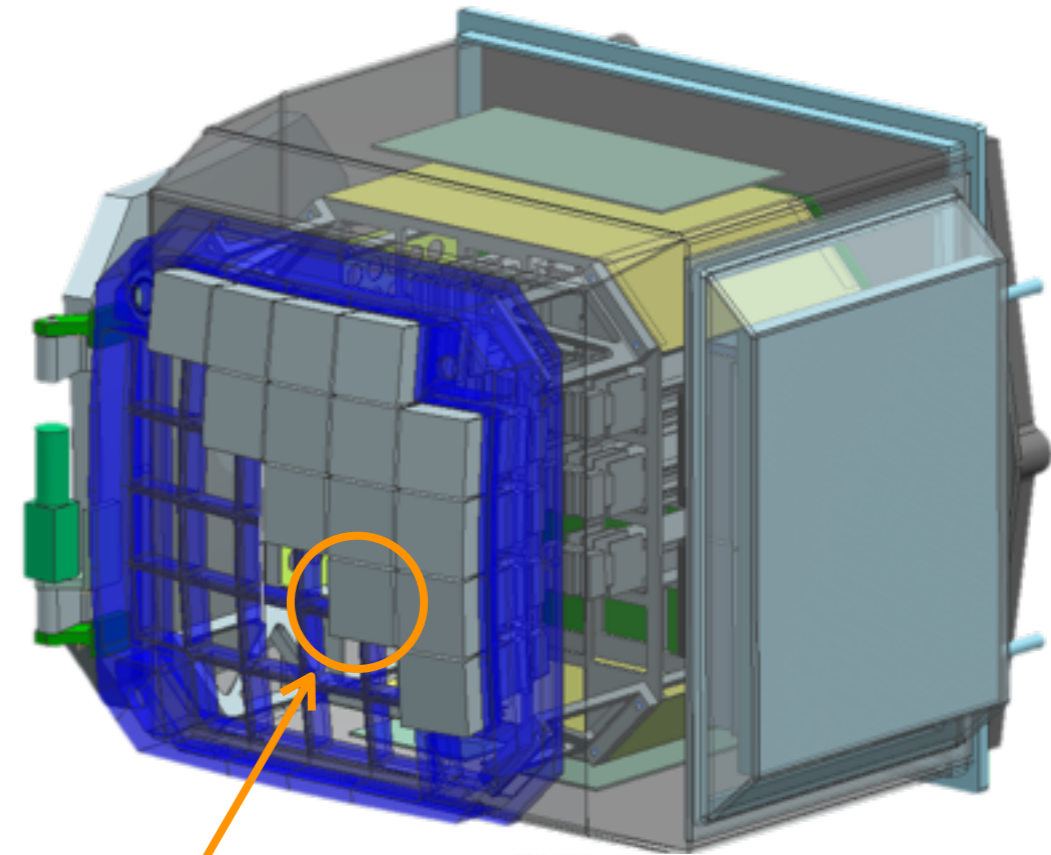




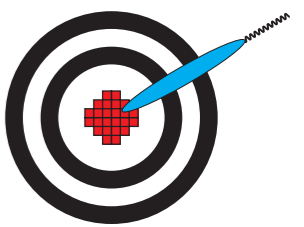
❖ SC-SST camera parameters

	32 mod
FOV for 0.18°/pixel (36 mm/°)	8.6°
FOV for 0.28°/pixel (23 mm/°)	13.4°
Angular pixel size for FOV=10°	0.21°
# of pixels per camera	2,048
Power consumption per camera (FE)	350 W
Weight per camera (FE+SiPM)	11 kg
Total cost (FE+SiPM) for 50 CAMs*	\$7.2M

*Assuming \$20/ch, which does not explicitly include labor for mechanical module assembly and calibrations

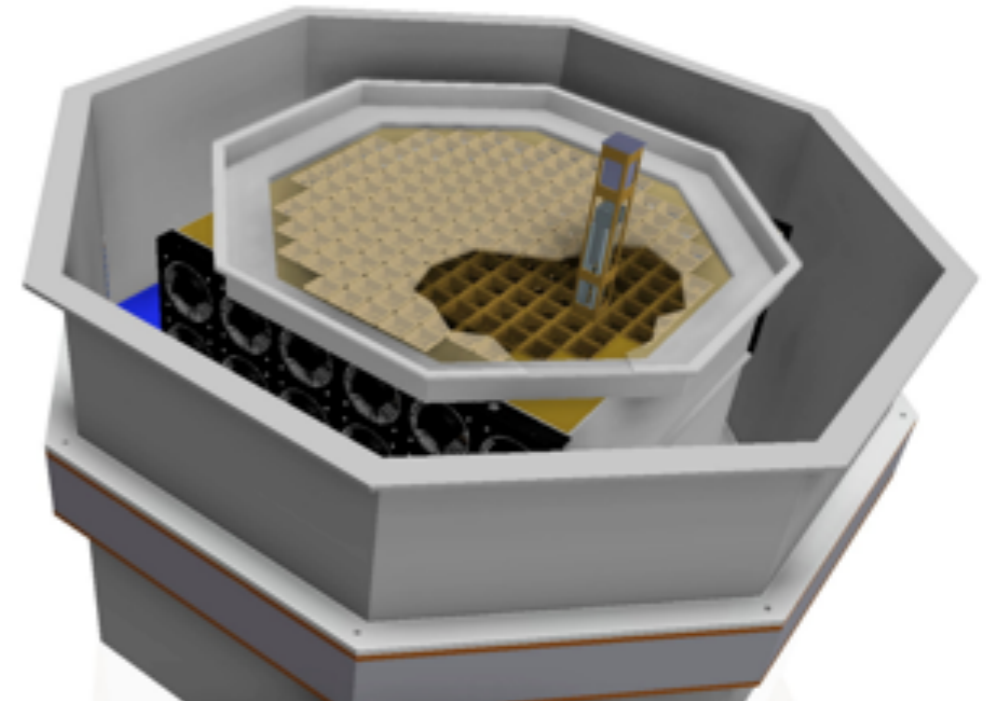


Front-End (FE) electronics module

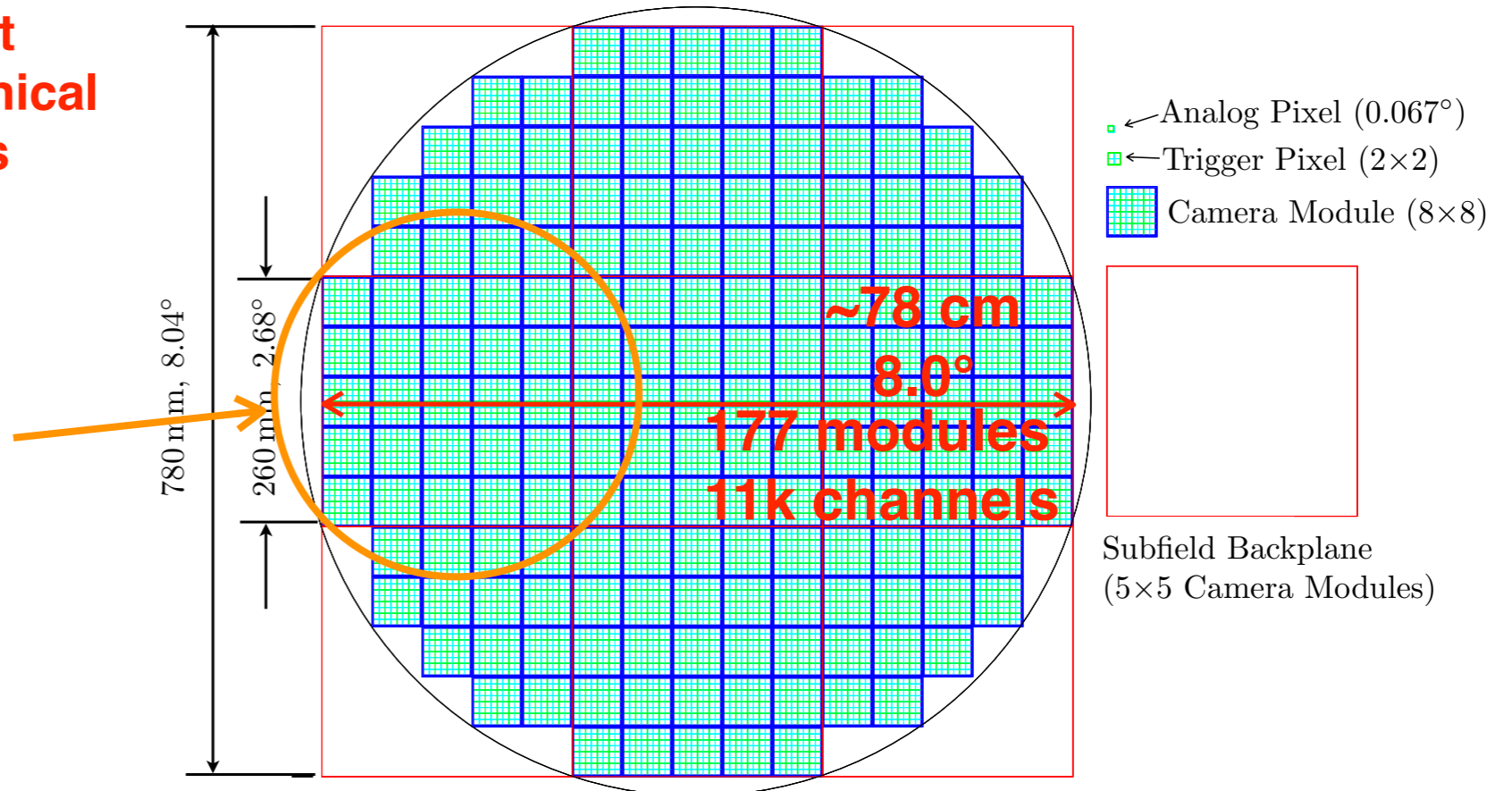
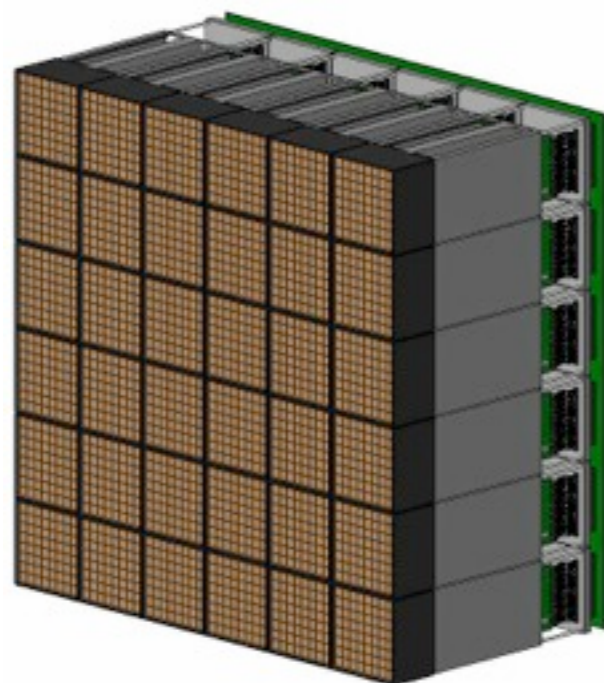


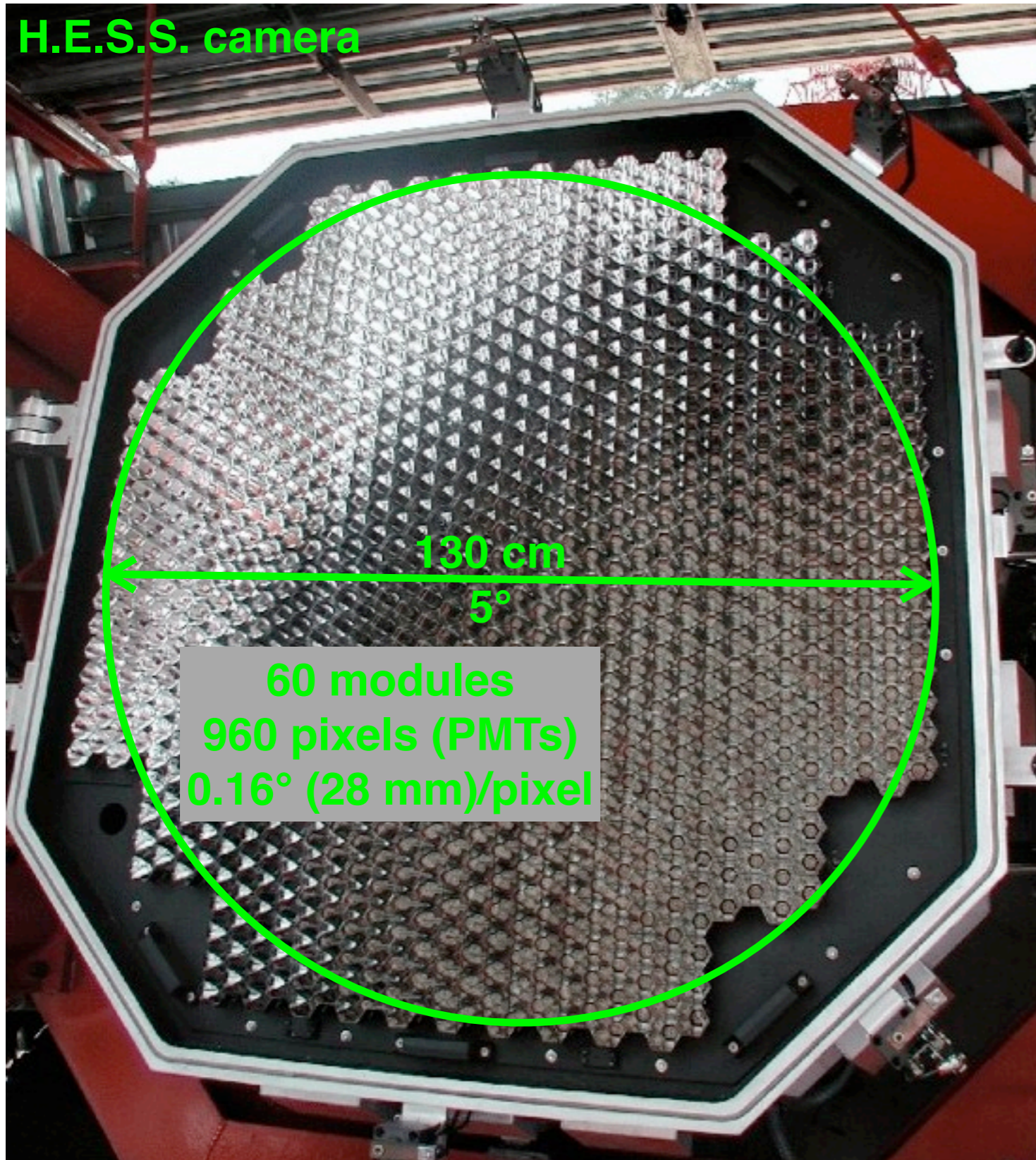
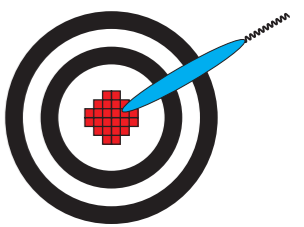
❖ SC-MST camera parameters

FOV	8.0°
Angular pixel size	0.067°
# of pixels per camera	11,328
Power consumption per camera (FE)	2000 W
Weight per camera (FE+SiPM)	61 kg
Total cost (FE+SiPM) for 50 CAMs*	\$24M

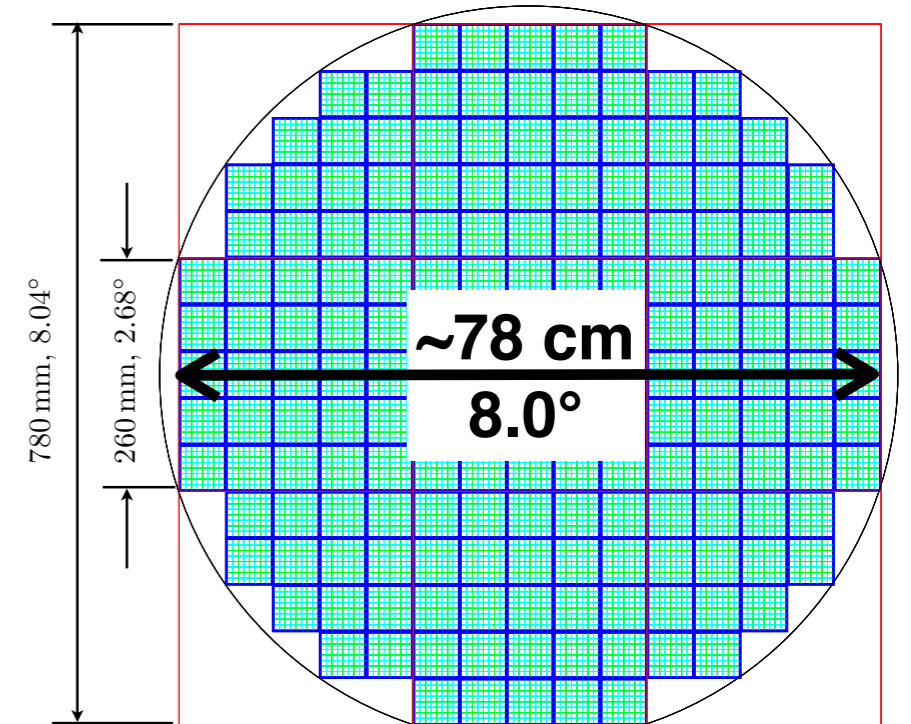


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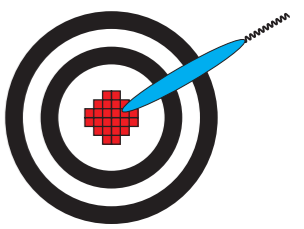




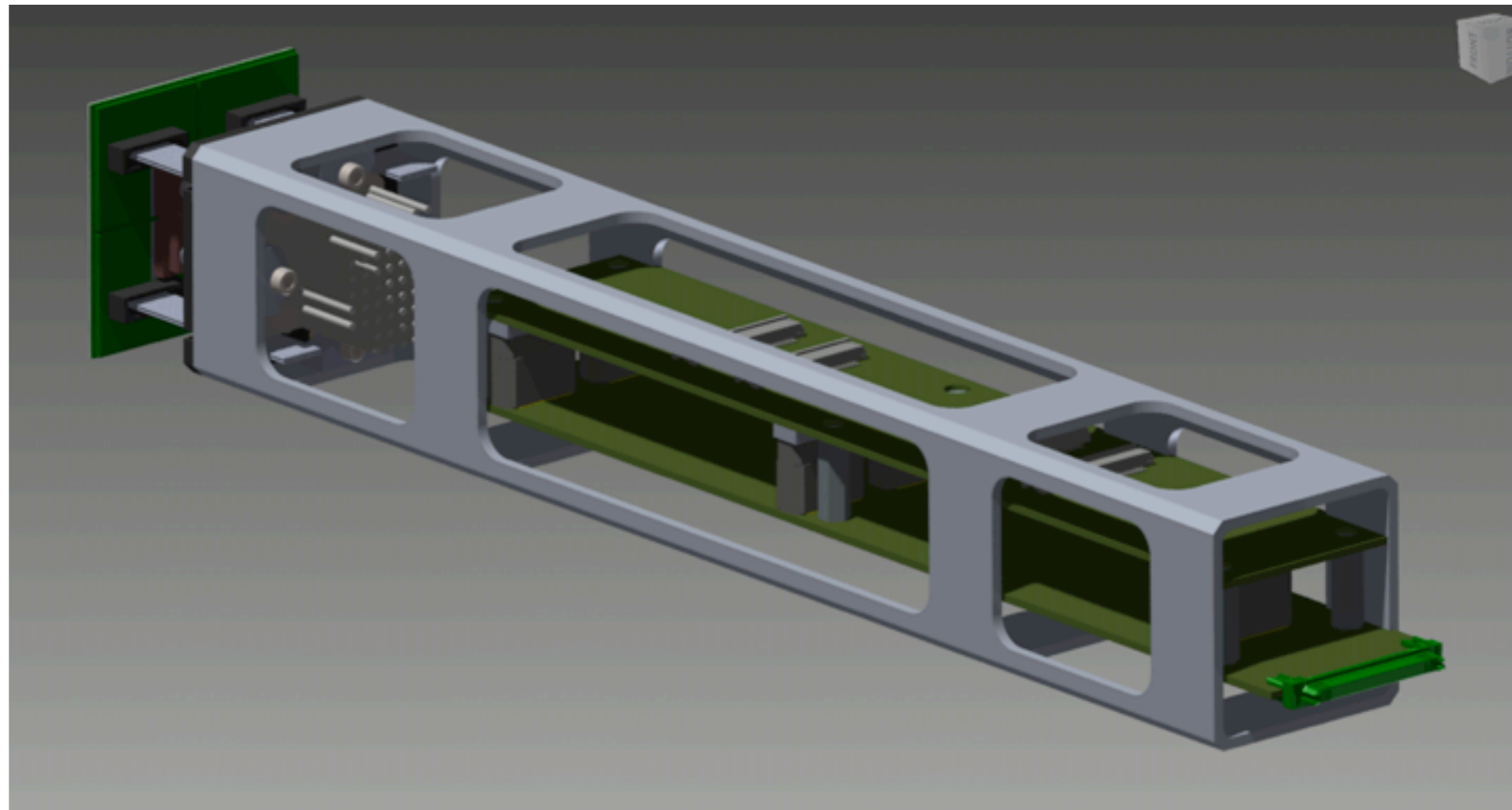
SC-MST camera

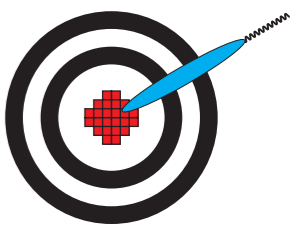


177 modules
11k pixels
0.064° (6.2 mm)/pixel

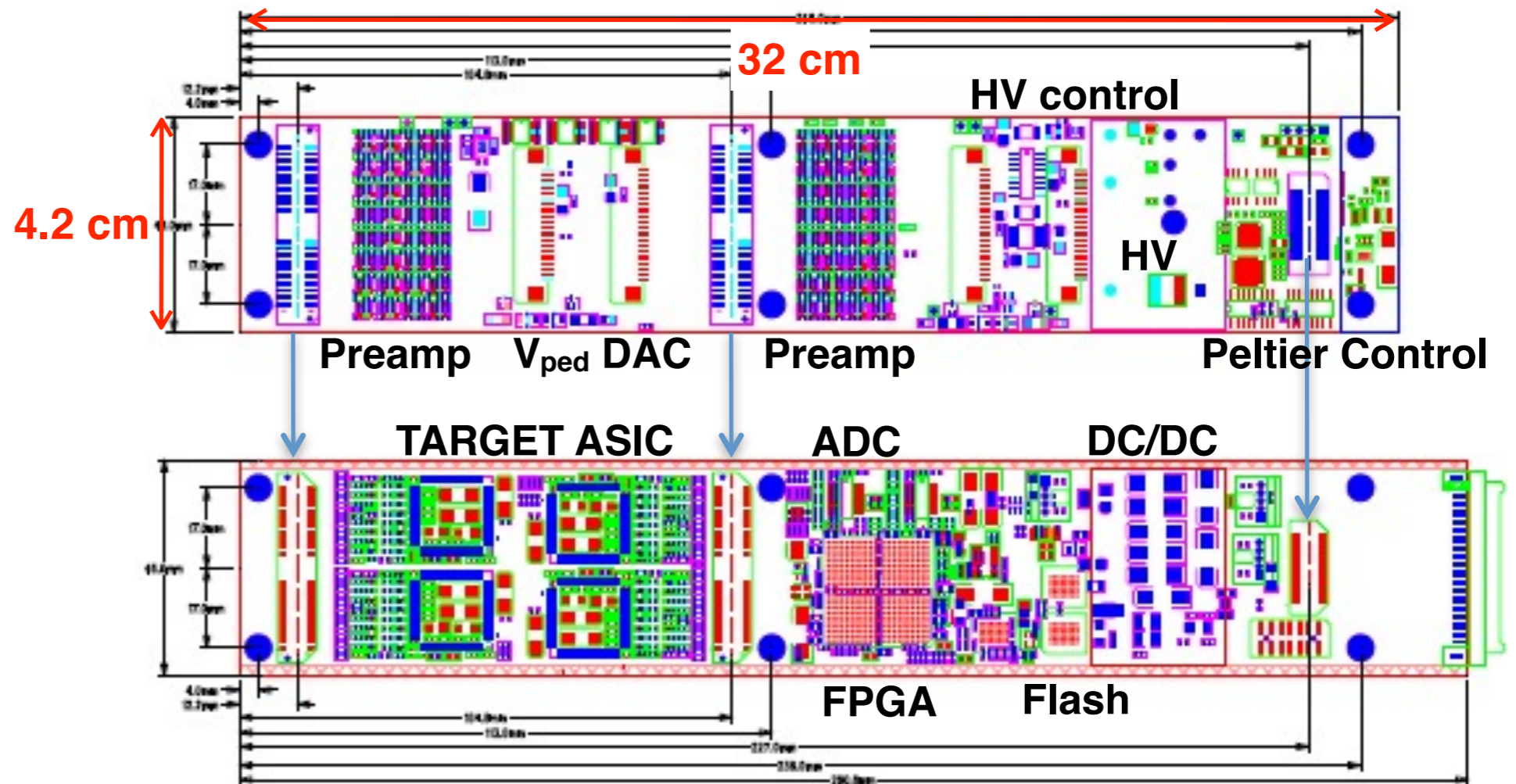


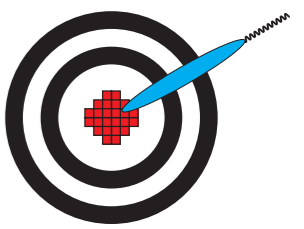
- ❖ **Board configuration**
 - ❖ **Photosensor I/F board: preamp, high voltage (HV), Peltier control**
 - ❖ **Signal processing board: TARGET ASIC, FPGA, back-end I/F, power supply**
- ❖ **Minimize # of components for cost reduction and reliability**
 - ❖ **Integration of necessary functionalities into an ASIC**



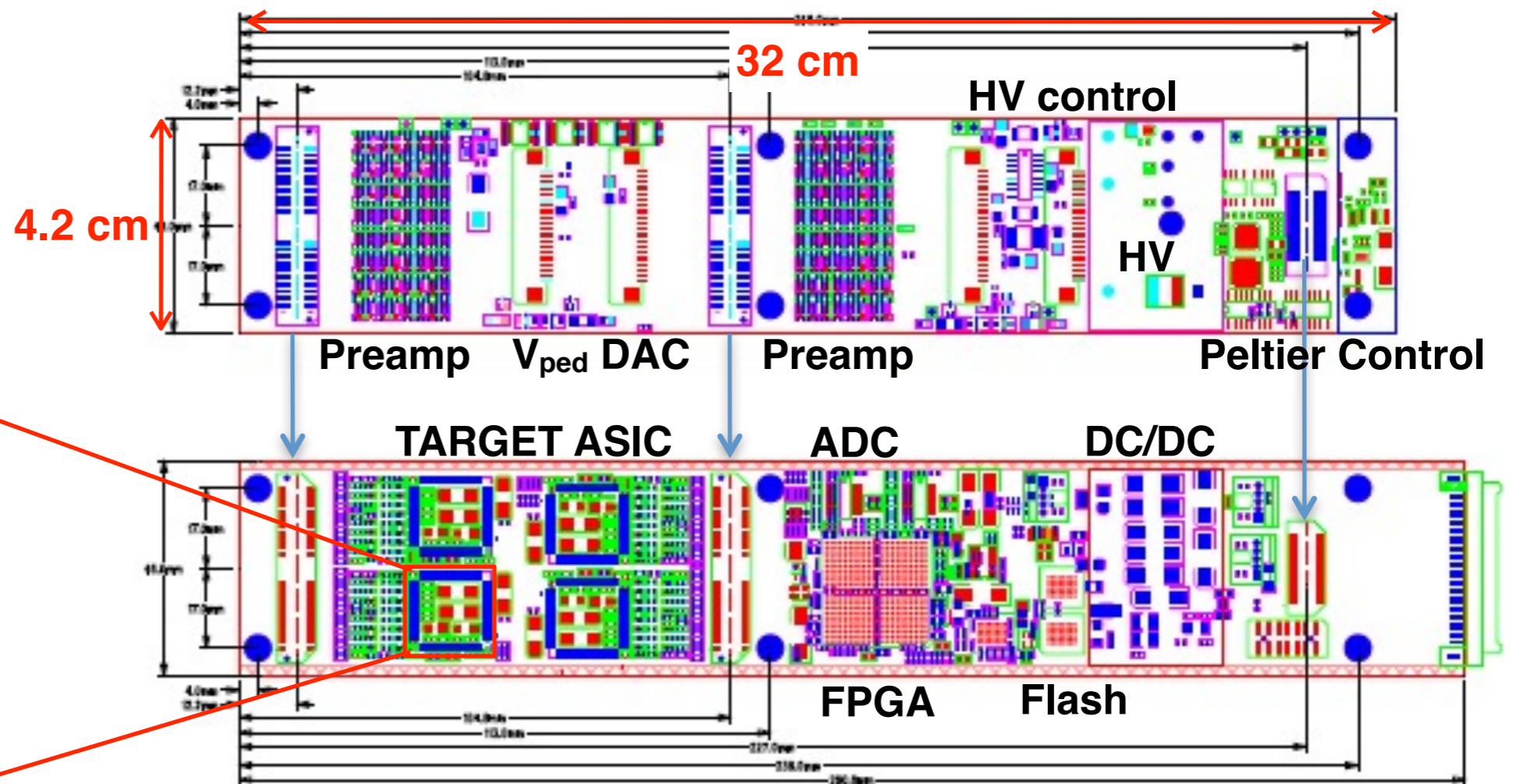


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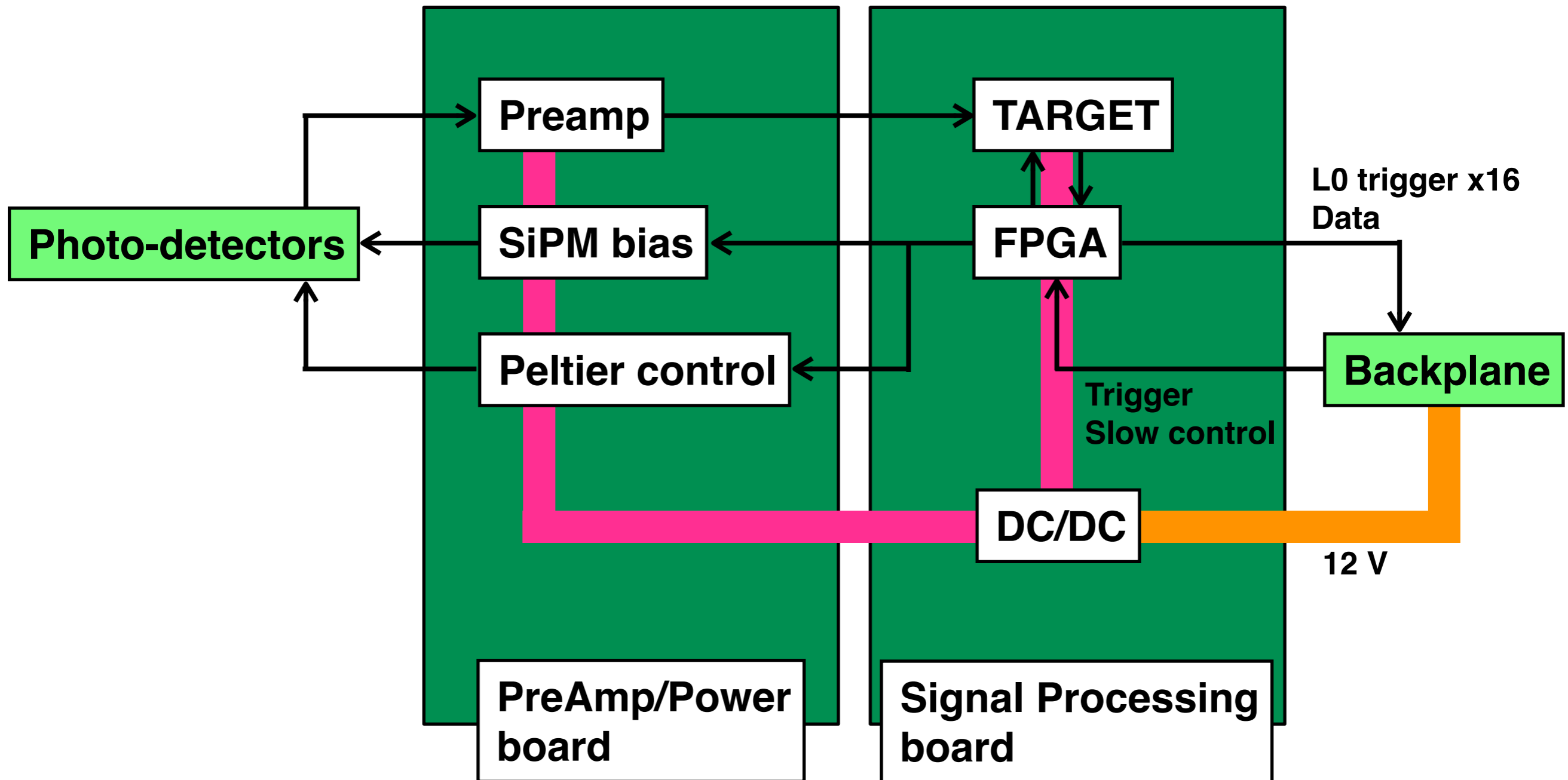
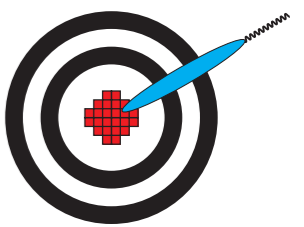


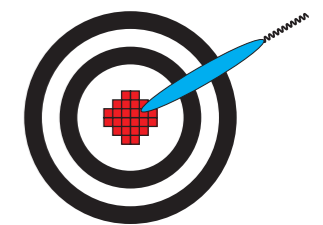
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designed by G. Varner
(Hawaii)

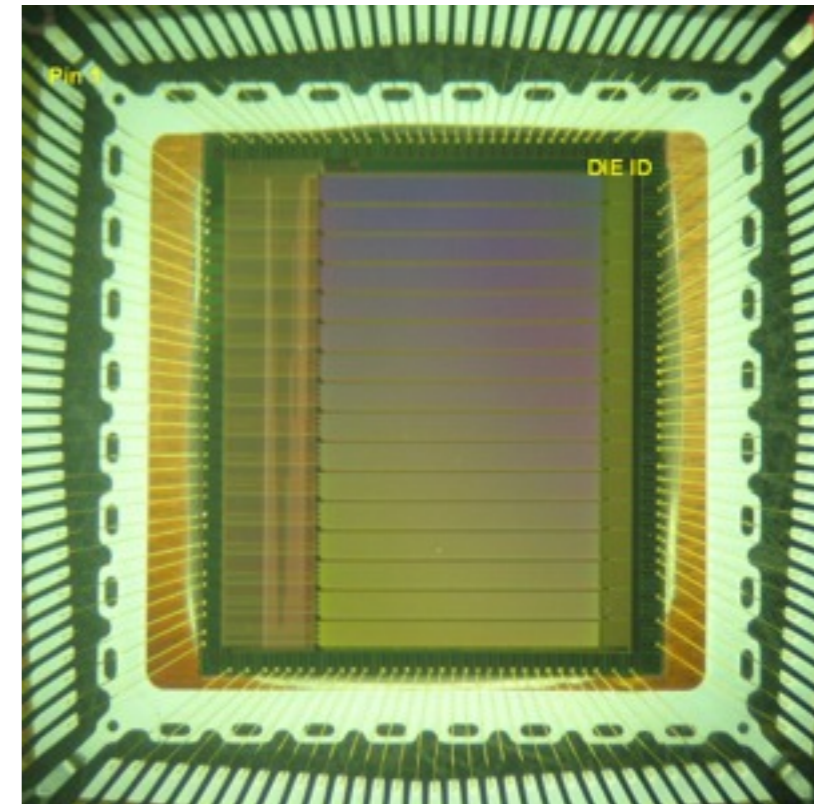
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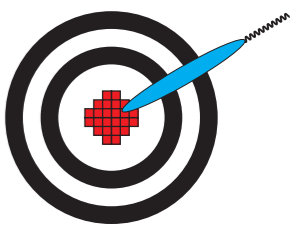
❖ Requirements

- ❖ **Waveform sampling at ~ 1 GSa/s**
- ❖ **Signal bandwidth > 380 MHz**
- ❖ **Cross-talk $< 1\%$**
- ❖ **Look-back time: $> 12 \mu\text{s}$**
- ❖ **Dynamic range: > 9 bits**
- ❖ **Readout (dead) time: $< 30 \mu\text{s}$**
- ❖ **Trigger timing: < 4 ns**
- ❖ **Trigger segment: $0.1^\circ \times 0.1^\circ \sim 0.2^\circ \times 0.2^\circ$**



❖ TARGET ASIC

- ❖ **Switched capacitor array for high speed waveform sampling**
- ❖ **Integrated digitization circuits and trigger circuits**
 - ◆ **Reduction of components and cost, increase reliability**
- ❖ **Internal bias generator**
 - ◆ **All digital interface**
- ❖ **Low power consumption: ~ 70 mW/channel including FPGA**



❖ TARGET-1

- ❖ 2008/May delivery
- ❖ BW is limited to ~150 MHz, 8k cells, no analog sum trigger

❖ TARGET-2/TARGET-4

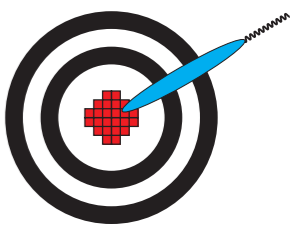
- ❖ 2011/Aug (TARGET-2), 2012/Feb (TARGET-4)
- ❖ Improved BW and cross talk, 16k cells, more (faster) digitization circuits, 4-ch analog sum trigger
- ❖ Problem with serial register loading, DAC voltage routing

❖ TARGET-5

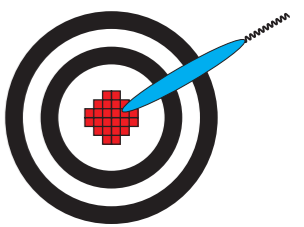
- ❖ 2012/Aug delivery
- ❖ BW is confirmed up to 400 MHz, cross talk < 1%
- ❖ Minimum trigger threshold is too high (~25 mV, ~6 p.e.)

❖ TARGET-7

- ❖ 2013/Sep submission, Dec delivery (expected)
- ❖ Wider dynamic range, better linearity and better temperature stability
- ❖ Lower trigger threshold (<10 mV, 2.5 p.e.)



		TARGET-5	TARGET-7
# of channels		16	16
# of cells/channel		16,384	16,384
Sampling frequency		0.4 – 1.2 GHz	0.5, 1.0 GHz
Bandwidth		> 380 MHz	> 380 MHz
Crosstalk (@ -3dB)		< 1%	< 1%
Dynamic range		0.6–1.0 mV/1.5 V	0.6–1.0 mV/2 V
Wilkinson ADC clock speed		~700 MHz	~500 MHz (external, both edges)
Digitization time		5.9 μ s (12 bit)	8.2 μ s (12 bit)
# of cells/digitization		32 cells x 16 ch	32 cells x 16 ch
Data transfer speed		~90 Mbps x 16 ch	~90 Mbps x 16 ch
Dead time (48 cells/ch)	10 bit	2.9 + 8 μ s	4.1 + 8 μ s
	12 bit	11.7 + 8 μ s	16.4 + 8 μ s
# of trigger output		4 (4 ch analog sum) + 1 (16 ch analog sum)	4 (4 ch analog sum, no gain adjustment)
Trigger threshold at input		25 mV minimum	10 – 80 mV (2.5 – 20 p.e. for MST) 0.2 mV step (nominal, 0.05 p.e. for MST)
Trigger threshold noise		< 4 mV	< 1.6 mV (rms)
Trigger gain adjustment		20%	None



❖ SC-MST prototype

❖ Partially populated mirrors and SiPM camera modules

- ◆ Comprehensive study of the structure, mirrors, motorization and control system

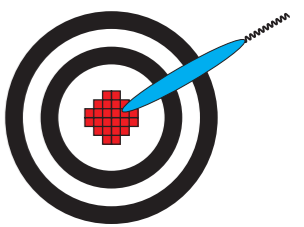
❖ SC-SST prototype

❖ Mini-array: 5 complete telescopes and cameras

- ◆ 1 MAPM camera + 4 SiPM cameras

❖ Test array performance, conduct scientific observations

	2013	2014				2015			
	Q4	Q1	Q2	Q3	Q4	Q1	Q2	Q3	Q4
SC-SST	32x MAPM modules	MAPM camera assembly		lab test	field test			Mini-array	
		32x SiPM modules	SiPM camera assembly		lab test	field test			
SC-MST		25x SiPM modules	SiPM camera assembly	lab test	field test				



- ❖ **Waveform sampling capability of TARGET-5 is satisfactory**
 - ❖ **Trigger performance will be fixed by TARGET-7 with better dynamic range and linearity**
- ❖ **Characterization and improvement of SiPM ongoing**

22pSD7: 日高直哉

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❖ Plans

- ❖ **TARGET-7 will be submitted for fabrication in 2013/Sep**
- ❖ **Prototype production started**
 - ◆ **SC-SST mini-array**
 - ◆ **SC-MST partial telescope**